FY2016
Financial Results Briefing

May 19, 2017

MEIKO ELECTRONICS CO., LTD.

(Securities Identification Code: 6787)

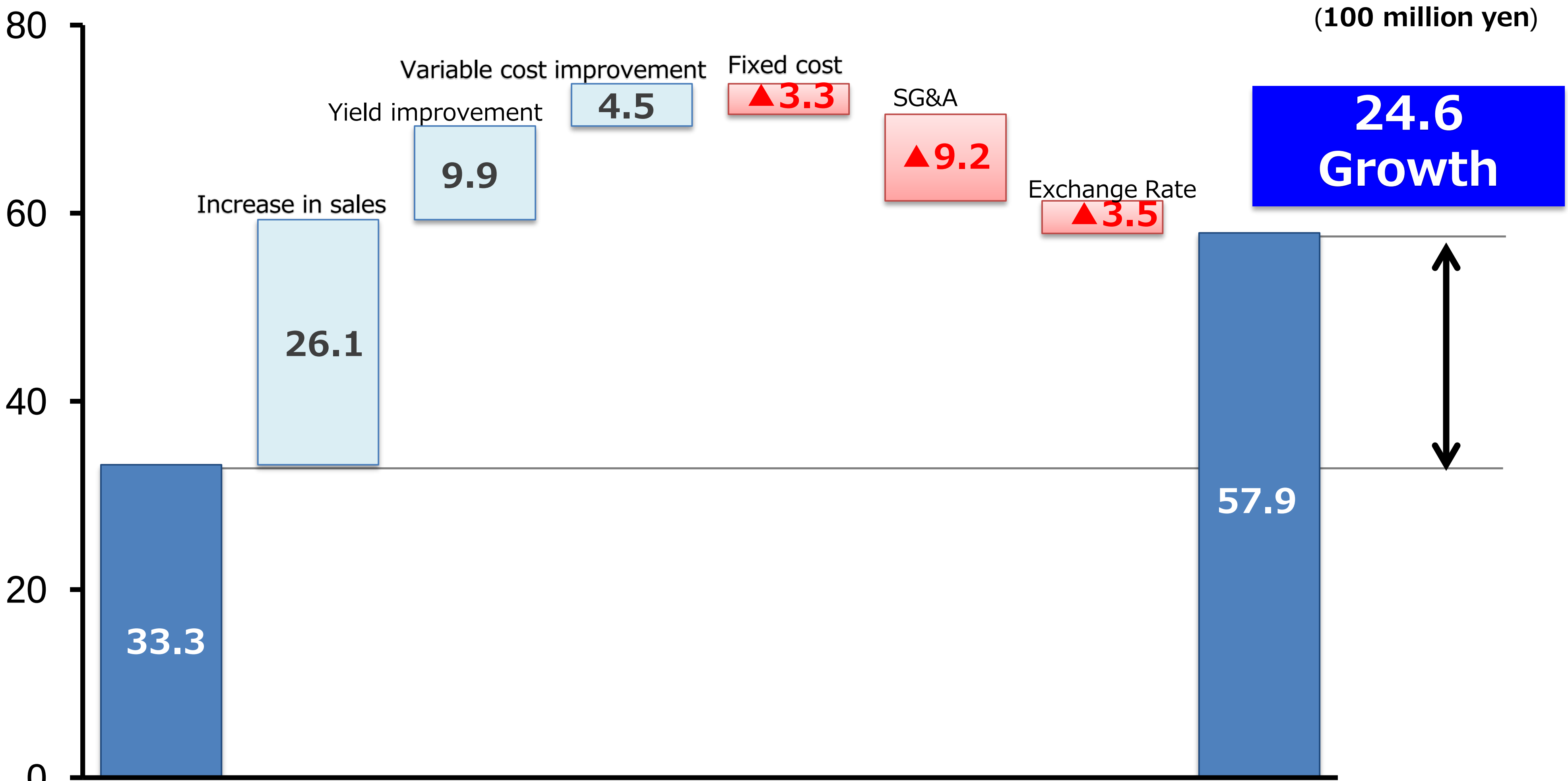
1	**FY2016 Results**
2	FY2017 Plan
3	Industry trends
4	Technology roadmap

FY2016 Consolidated Business Performance

(100 million yen)

	FY2015 performance	FY2016 performance	Year-on-year	
			Increase	%
Net sales	952.9	959.1	+6.2	0.7%
Operating income	33.3 3.5%	57.9 6.0%	+24.6	73.9%
Ordinary income	▲4.9 ▲0.5%	29.8 3.1%	+34.7	-
Net income	▲112.5 ▲11.8%	17.7 1.8%	+130.2	-
Average Exchange rate (Yen/USD)	120.12	108.69		

Analysis of operating profit change FY2015→FY2016

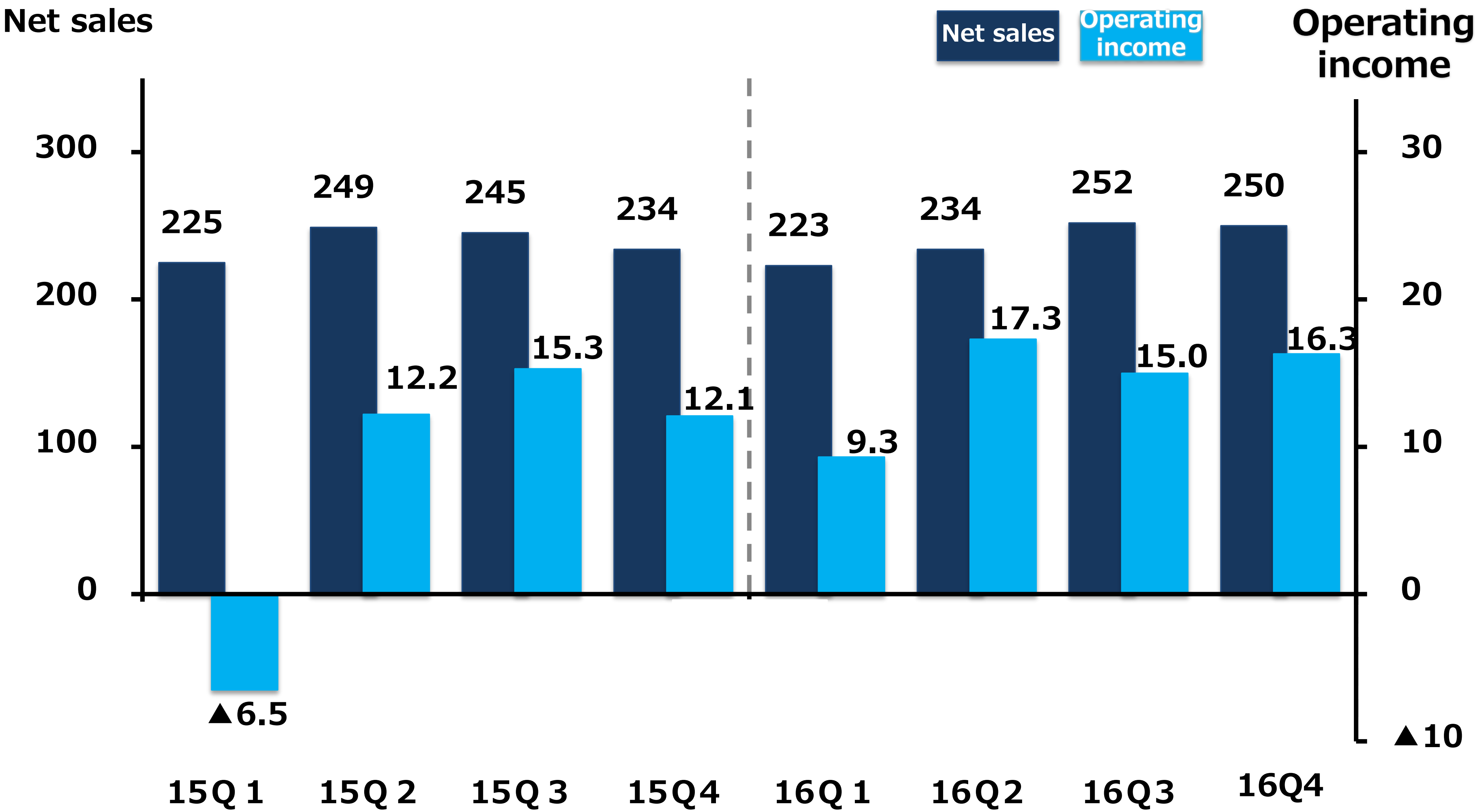


FY2015 performance
(Exchange rate 120.12yen/us$)

FY2016 performance
(Exchange rate108.69yen/us$)

Net sales , Operating income

(100 million yen)

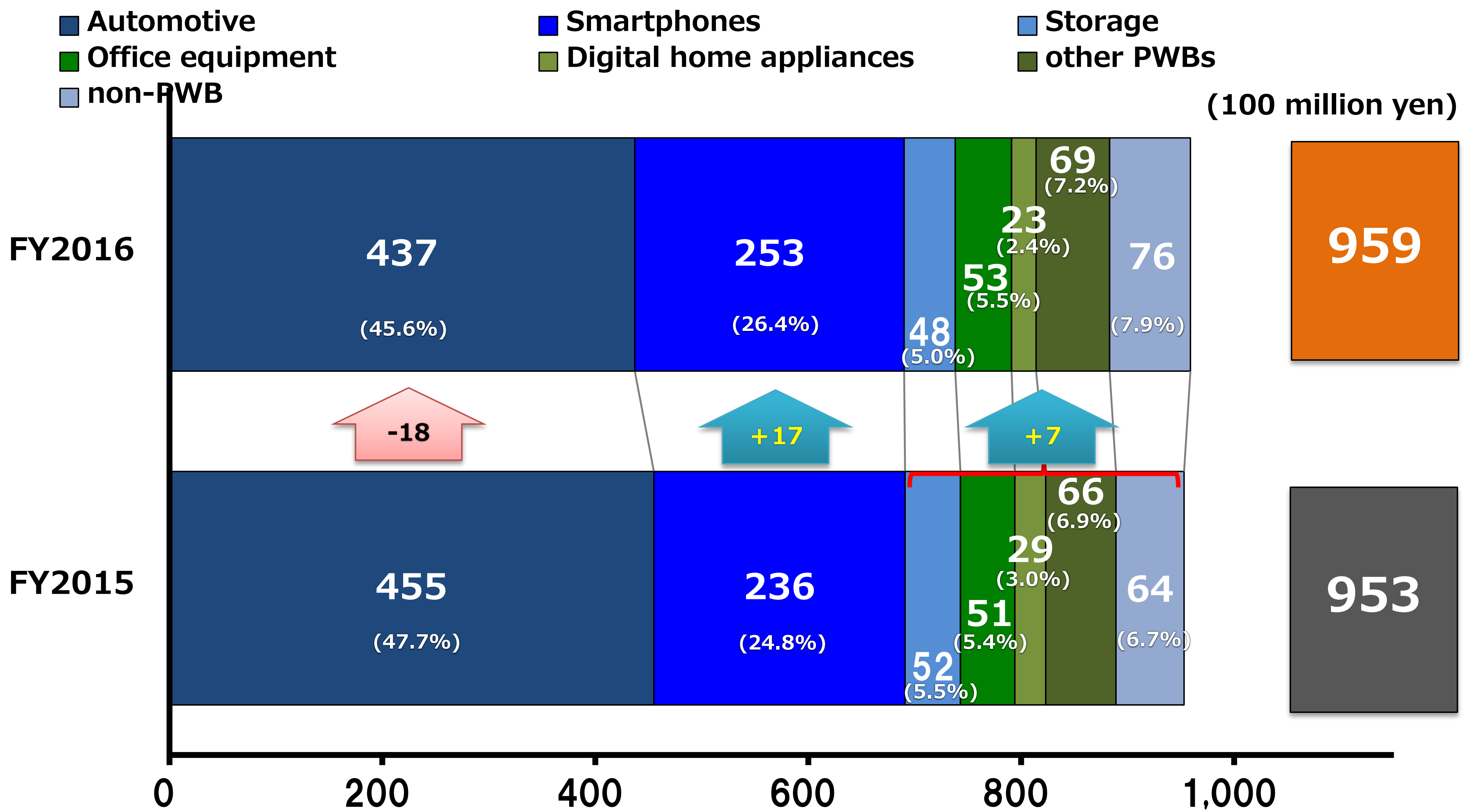


Overseas plants-Financial results FY2016

(100 million yen)

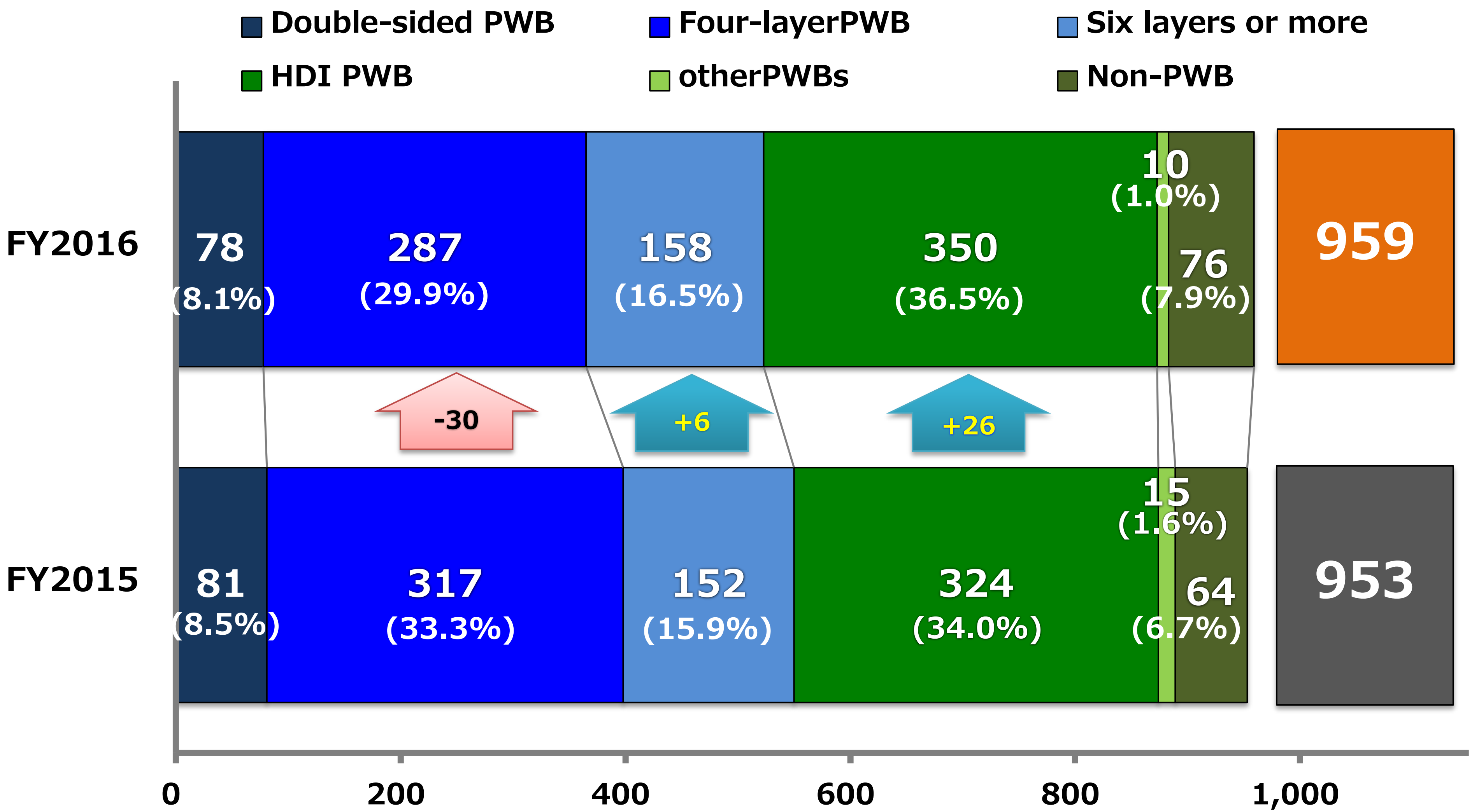
		FY2015 performance	FY2016 performance	Year-on-year	
				Increase	%
Guangzhou	Net sales	319	284	-35	-11.0%
	Operating income	17	17	0	0.0%
		5.3%	6.0%		
Wuhan	Net sales	320	358	+38	11.9%
	Operating income	5	21	+16	320.0%
		1.6%	5.9%		
Vietnam	Net sales	166	192	+26	15.7%
	Operating income	9	20	+11	122.2%
		5.4%	10.4%		
Average Exchange rate (Yen/USD)		120.12	108.69		

By product Application



By product specification

(100 million yen)



Consolidated financial prospect for FY2017

(100 million yen)

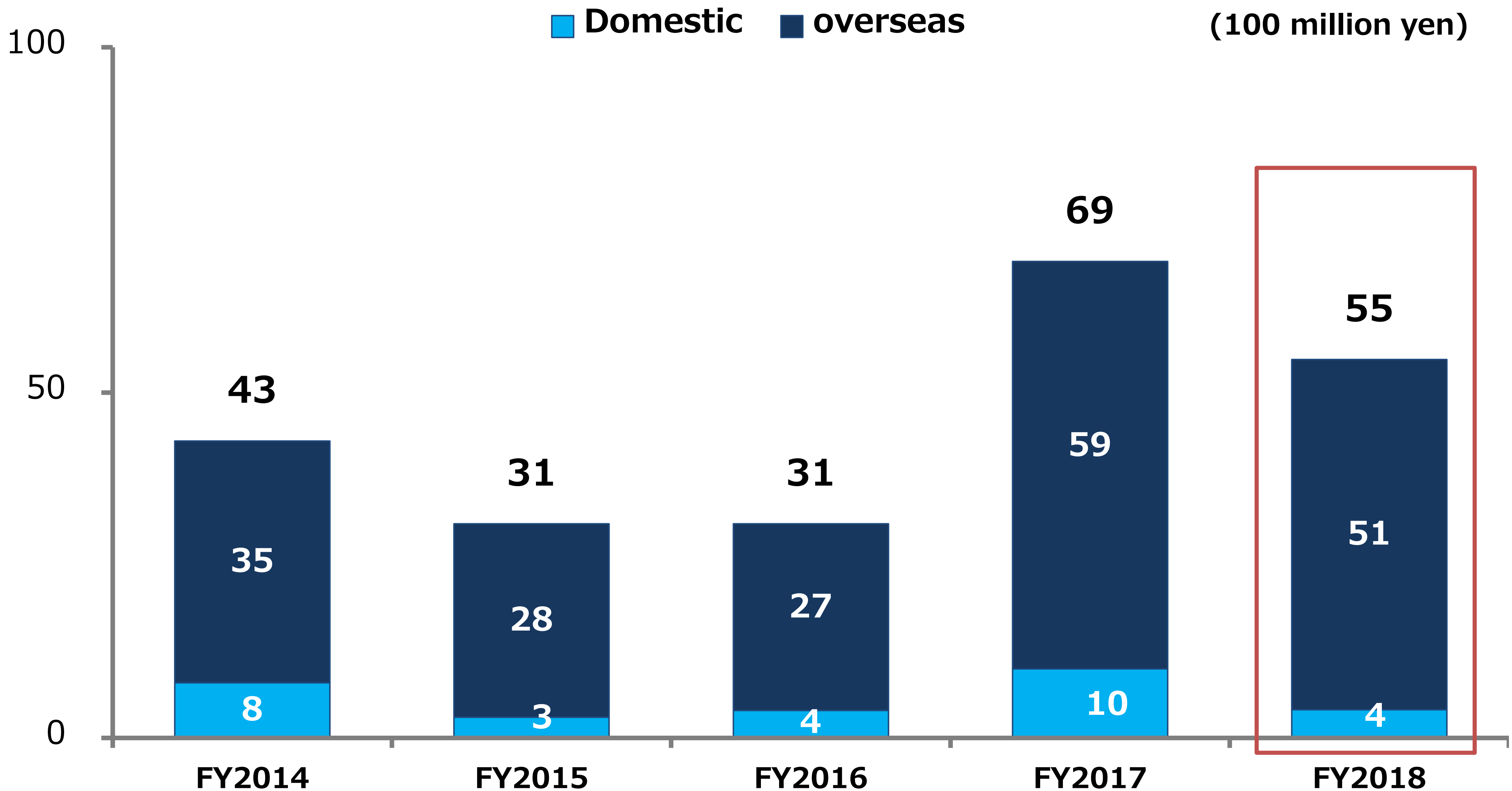
	FY2016	FY2017	Year-on-year	
			Increase	%
Net sales	959.1	1,030.0	+70.9	7.4%
Operating income	57.9	62.0	+4.1	7.1%
	6.0%	6.0%		
Ordinary income	29.8	46.0	+16.2	54.4%
	3.1%	4.5%		
Net Income	17.7	36.0	+18.3	103.4%
	1.8%	3.5%		
Average Exchange rate (Yen/USD)	108.69	110.00		

FY2017 Sales plan for Overseas plants

(100 million yen)

		FY2016	FY2017	Year-on-year	
				Increase	%
Guangzhou	Net sales	284	250	-34	-12.0%
	Operating income	17	15	-2	-11.8%
		6.0%	6.0%		
Wuhan	Net sales	358	373	15	4.2%
	Operating income	21	22	1	4.8%
		5.9%	5.9%		
Vietnam	Net sales	192	238	46	24.0%
	Operating income	20	25	5	25.0%
		10.4%	10.5%		
Average exchange rate (Yen/USD)		108.69	110.00		

FY2017 Investments



Depreciation	71	64	55	58

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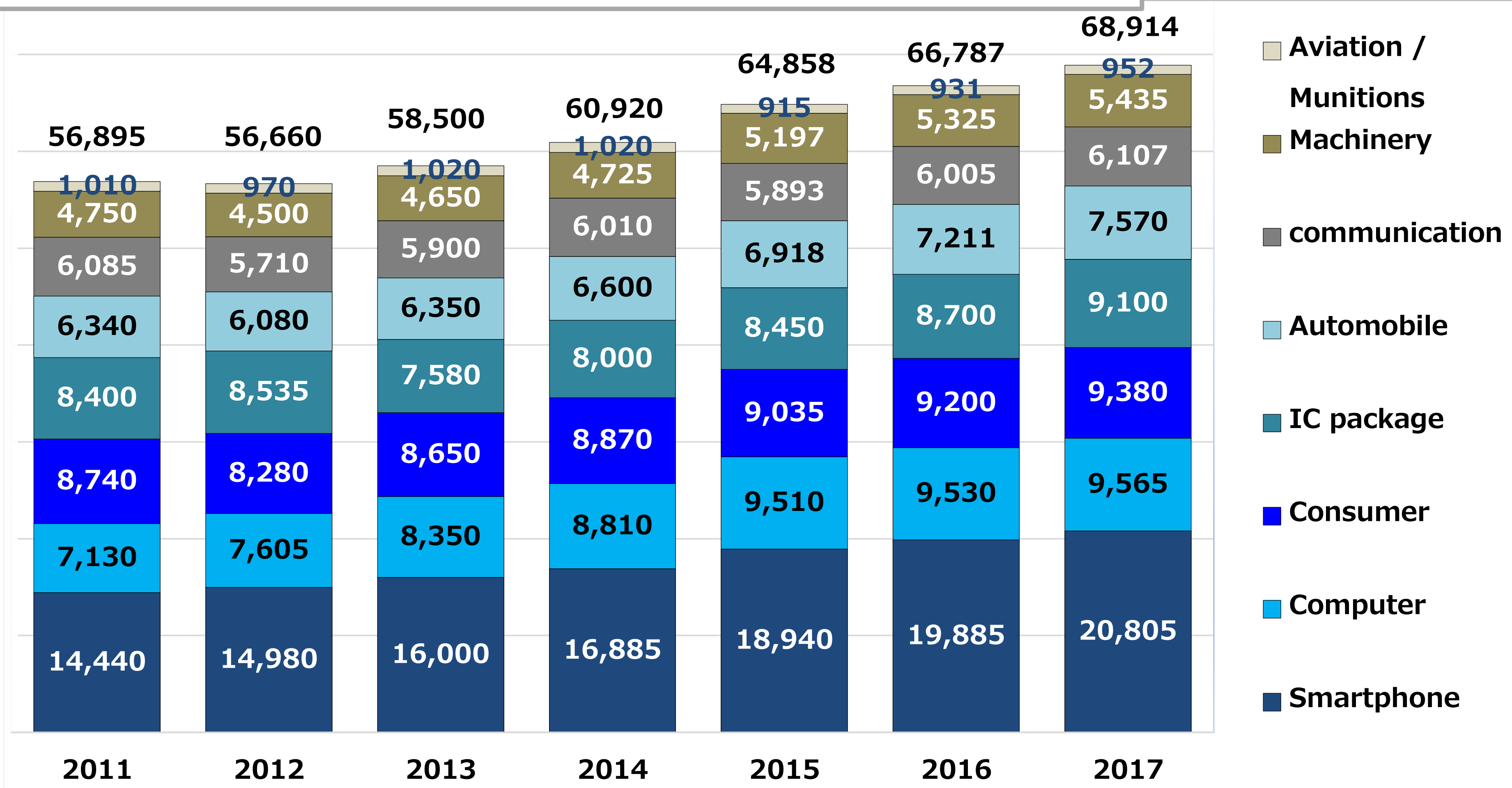
3	**Industry trends**
4	Technology roadmap

Industry trends –summary-

Expansion trend continues mainly in smartphones and automotive markets

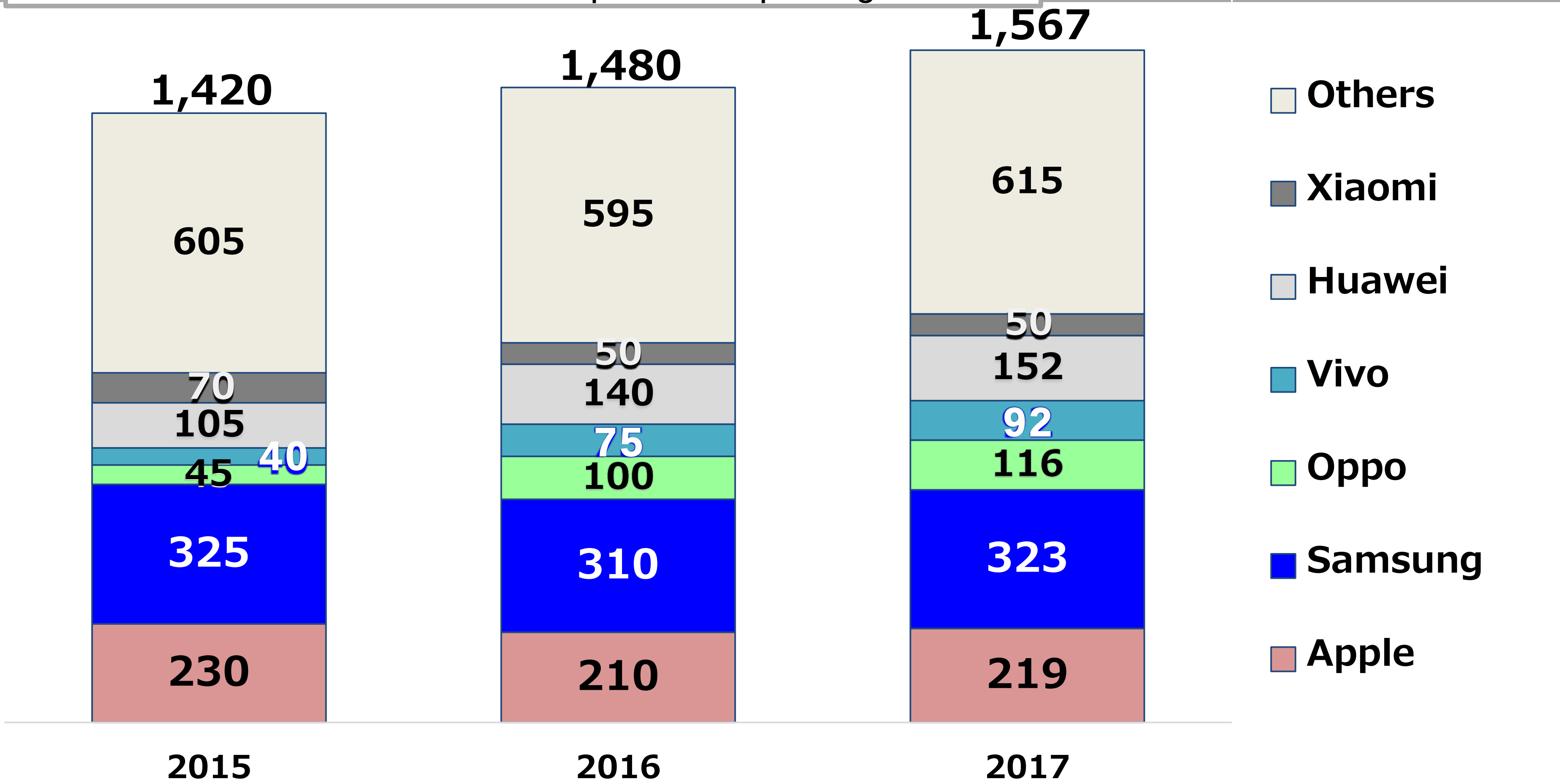


Source：JMS

Industry trends –smartphone-

In the global market, in addition to the global 2 big companies, the shares of Chinese companies keep rising

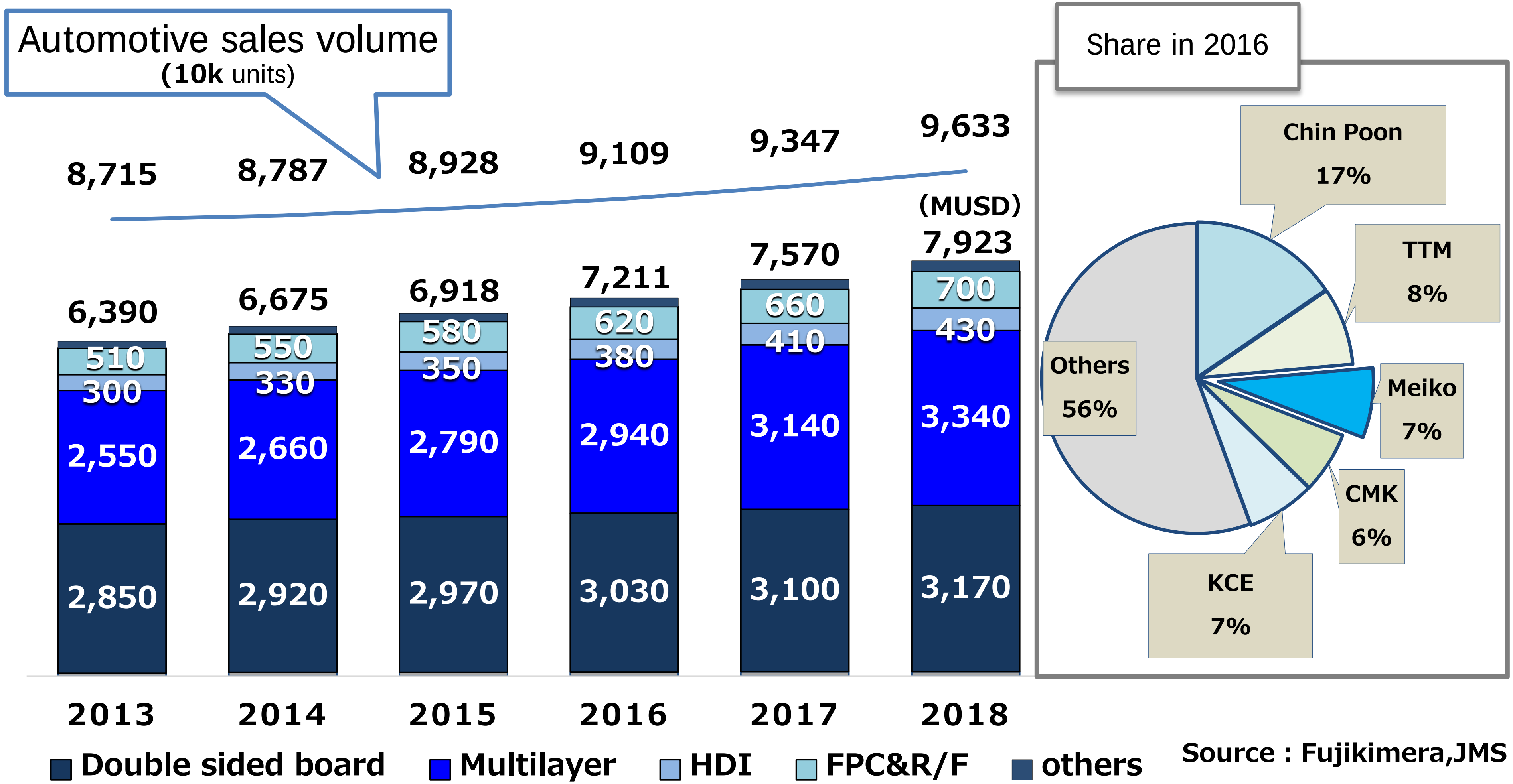
(1 million units)



Source : Fujikimera、EMC

Industry trends –Automobile-

Usage of PWBs in cars is growing faster than the car sales growing rate.



Source : Fujikimera,JMS

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Automotive Technology Trend

Emission Regulation	130 (g/km)	95 (g/km)	Power train
Electrification	Hybrid, Plug-in Hybrid	Electric, Fuel Cell	Body
advanced driver assistance system	Level 2	Level 3	Driving safety
Connected car	System Integration	5G	Communication
Electrical installed	>50%		Information

2017年 2020年 202X年

High speed / high frequency
Sensing

High speed
wide area communication
System integration

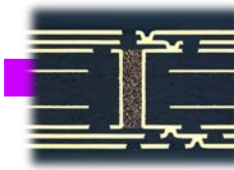
Large current / high voltage
High heat dissipation

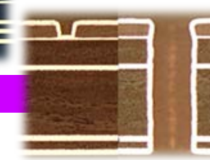
Compact and lightweight
High heat dissipation

Electro-mechanical integrated

In-vehicle PWB technology roadmap

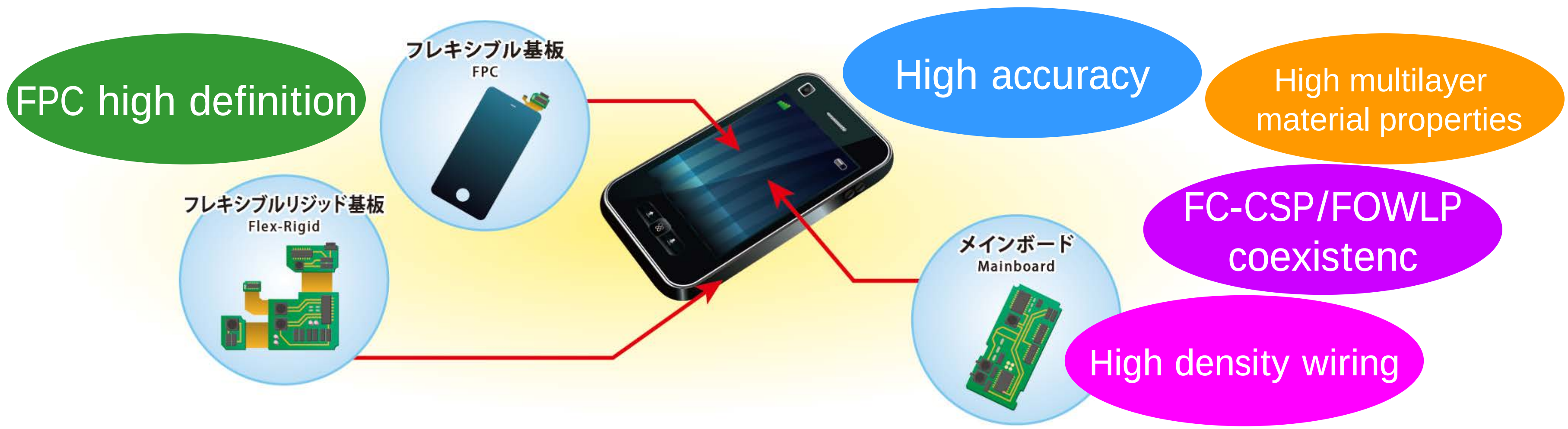
	Automotive technology	Substrate technology	2017	2020	202X
Communication	Communication module	High density module substrate	Evaluation		
Information	0.4 / 0.5 pitch CSP	Multi-Layer HDI	Evaluation		
Body	LED lighting	Metal base heat dissipation board	Trial		
Body	Miniaturization and lightweight	Copper inlay heat dissipation board	Trial		
Power train	Power IC heat dissipation	Component built-in board	Trial		
Driving safety	High speed Transmission lines	Impedance control board	Trial		
Driving safety	High frequency support	Millimeter wave radar board	Trial		





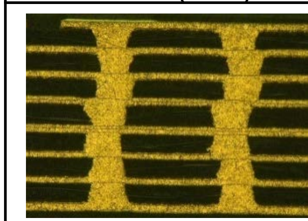
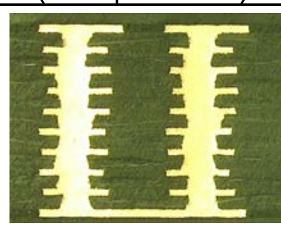
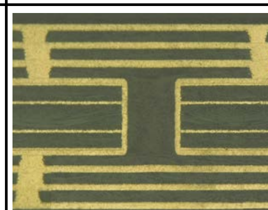
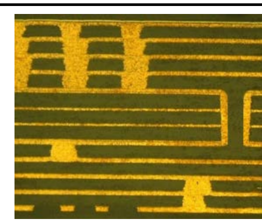
Smartphone PWB technology roadmap

Mobile communication	4G	5G	Electronic parts
Data transmission speed	100M-1Gbps	10Gbps, USB3.1	High speed transmission
Application processor	Flip-Chip CSP	FOWLP	Low profile
Display panel	liquid crystal	AMOLED	COF
Battery	Large capacity		Main board Miniaturization
	2017	2019 2021	

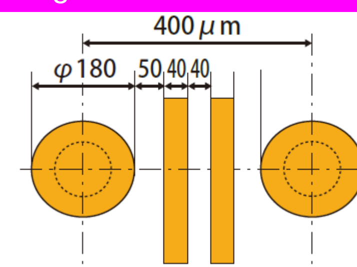


Smartphone mainboard technology roadmap

Electronic parts	Main IC/Sub IC	0.4/0.35mmPitch	0.35/0.3mmPitch
High Layer Ctn	Flagship Midrange/High end	12Layer(5-2-5) 10Layer(2-6-2/3-4-3)	14Layer(6-2-6) 12Layer(3-6-3/4-4-4)
Material properties	Dielectric constant /Heat-resistant	Dk3.5/Tg170°C	Dk3.5/Tg190℃
High density wiring	Line/Space Via/Land	L/S=40/40um 85/180um	L/S=30/40um 75/150um
＜Smartphone technology＞	＜Substrate technology＞	2017	2019 2021

8 layer Any layer	10 - 12 layer Any layer	10Layer(3-4-3)	12Layer(4-4-4)
Low dielectric material(2013)	Flagship (Mass production)	Mid-range model	High end model
			

Main IC mounting part
Wiring rule



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